

L Number	Hits	Search Text	DB	Time stamp
-	163	(IC adj package).ti.	USPAT; US-PGPUB	2003/08/13 15:59
-	216	(IC adj package).ti.	USPAT; US-PGPUB	2003/03/22 11:05
-	16	((IC adj package).ti.) and 324/\$.ccls.	USPAT; US-PGPUB	2003/03/22 11:15
-	2	((IC adj package).ti.) and 439/\$.ccls.) and bond	USPAT; US-PGPUB	2003/03/22 11:14
-	1	((IC adj package).ti.) and 324/\$.ccls.) and bond	USPAT; US-PGPUB	2003/03/22 11:14
-	432	324/\$.ccls. and package and adhesive and chip	USPAT; US-PGPUB	2003/03/22 11:15
-	280	324/\$.ccls. and package and adhesive and chip and bond	USPAT; US-PGPUB	2003/03/22 11:15
-	19	324/\$.ccls. and package and adhesive and chip and bond and indium	USPAT; US-PGPUB	2003/03/22 12:42
-	36	((IC adj package).ti.) and 439/\$.ccls.	USPAT; US-PGPUB	2003/03/22 11:49
-	5166	(package near comprising).clm.	USPAT; US-PGPUB	2003/03/22 11:50
-	0	((package near comprising).clm.) and conductive near2 adhesive	USPAT; US-PGPUB	2003/03/22 11:53
-	1	((package near comprising).clm.) and ECA	USPAT; US-PGPUB	2003/03/22 11:51
-	55	((package near comprising).clm.) and 324/\$.ccls.	USPAT; US-PGPUB	2003/03/22 11:52
-	0	((package near comprising).clm.) and 324/\$.ccls.) and adhesive	USPAT; US-PGPUB	2003/03/22 11:52
-	194	((package near comprising).clm.) and conductive near2 adhesive	USPAT; US-PGPUB	2003/03/22 11:52
-	17	((package near comprising).clm.) and 324/\$.ccls.) and adhesive	USPAT; US-PGPUB	2003/03/22 11:53
-	194	((package near comprising).clm.) and conductive near2 adhesive	USPAT; US-PGPUB	2003/03/22 12:24
-	3	((package near comprising).clm.) and conductive near2 adhesive) and 324/\$.ccls.	USPAT; US-PGPUB	2003/03/22 11:57
-	104	((package near comprising).clm.) and conductive near2 adhesive) and 257/\$.ccls.	USPAT; US-PGPUB	2003/03/22 11:58
-	94	((package near comprising).clm.) and conductive near2 adhesive) and 257/\$.ccls.) and bond\$	USPAT; US-PGPUB	2003/03/22 12:00
-	62	((package near comprising).clm.) and conductive near2 adhesive) and 257/\$.ccls.) and wire adj bond\$	USPAT; US-PGPUB	2003/03/22 12:03
-	41	((package near comprising).clm.) and conductive near2 adhesive) and 257/\$.ccls.) and wire adj bond\$) and (gold indium)	USPAT; US-PGPUB	2003/03/22 12:22
-	2	((package near comprising).clm.) and conductive near2 adhesive) and 257/\$.ccls.) and wire adj bond\$) and indium	USPAT; US-PGPUB	2003/03/22 12:22
-	3	((package near comprising).clm.) and adhesive with indium	USPAT; US-PGPUB	2003/03/22 12:24
-	3	324/\$.ccls. and package and adhesive with indium	USPAT; US-PGPUB	2003/03/22 12:55
-	2	439/\$.ccls. and package and adhesive with indium	USPAT; US-PGPUB	2003/03/22 12:55
-	23	257/\$.ccls. and package and adhesive with indium	USPAT; US-PGPUB	2003/03/22 12:55
-	2	"6489178"	USPAT; US-PGPUB	2003/03/22 13:29
-	2	("5151276" "5897338").PN.	USPAT	2003/03/22 13:29
-	1059	438/118-119.ccls.	USPAT; US-PGPUB	2003/03/22 13:51

	66	438/118-119.cccls. and indium	USPAT; US-PGPUB	2003/03/22 13:44
	2	438/118-119.cccls. and adhesive with indium	USPAT; US-PGPUB	2003/03/22 13:44
	1136	438/106.cccls.	USPAT; US-PGPUB	2003/03/22 13:53
	2	438/106.cccls. and adhesive with indium	USPAT; US-PGPUB	2003/03/22 13:52
	1394	438/14-15.cccls.	USPAT; US-PGPUB	2003/03/22 13:57
	227	438/14-15.cccls. and adhesive	USPAT; US-PGPUB	2003/03/22 13:54
	1	438/14-15.cccls. and adhesive with indium	USPAT; US-PGPUB	2003/03/22 13:54
	530	438/15.cccls.	USPAT; US-PGPUB	2003/03/22 13:57
	224	438/15.cccls. and therm\$	USPAT; US-PGPUB	2003/03/22 13:58
	0	(438/15.cccls. and therm\$) and indium	USPAT; US-PGPUB	2003/03/22 13:58
	16	(438/15.cccls. and therm\$) and indium	USPAT; US-PGPUB	2003/03/22 14:10
	2	(("6251696") or ("5994716")).PN.	USPAT; US-PGPUB	2003/03/22 14:10
	390	eutectic with indium	USPAT; US-PGPUB	2003/03/22 15:20
	6	(eutectic with indium) and 324/\$.cccls.	USPAT; US-PGPUB	2003/03/22 15:24
	574	aluminum with boron with beryllium with oxide	USPAT; US-PGPUB	2003/03/22 15:25
	766	aluminum with boron with beryllium with oxide	USPAT; US-PGPUB	2003/03/22 15:25
	192	aluminum with boron with beryllium with oxide with ceramic	USPAT; US-PGPUB	2003/03/22 15:26
	0	(aluminum with boron with beryllium with oxide with ceramic) and 324/\$.cccls.	USPAT; US-PGPUB	2003/03/22 15:25
	23	aluminum with boron with beryllium with oxide with ceramic with substrate	USPAT; US-PGPUB	2003/03/22 15:26
	31	semiconductor near2 thermal near2 sensor	USPAT; US-PGPUB	2003/03/22 15:56
	0	(semiconductor near2 thermal near2 sensor) and washer	USPAT; US-PGPUB	2003/03/22 15:57
	11	(semiconductor near2 thermal near2 sensor) and mount	USPAT; US-PGPUB	2003/03/22 16:44
	0	(semiconductor near2 thermal near2 sensor) and mount	EPO; JPO; DERWENT; IBM_TDB	2003/03/22 16:44
	20	semiconductor near2 thermal near2 sensor	EPO; JPO; DERWENT; IBM_TDB	2003/03/22 16:44
	2	(("6251696") or ("5126813")).PN.	USPAT; US-PGPUB	2003/03/22 17:27
	1	((("6251696") or ("5126813")).PN.) and size	USPAT; US-PGPUB	2003/03/22 17:28
	1	((("6251696") or ("5126813")).PN.) and mm	USPAT; US-PGPUB	2003/03/22 17:28
	688	438/17.cccls.	USPAT; US-PGPUB	2003/08/13 16:20
	3	438/17.cccls. and bonding adj condition	USPAT; US-PGPUB	2003/08/13 16:02
	0	438/17.cccls. and thermoelectroc	USPAT; US-PGPUB	2003/08/13 16:20
	2	438/17.cccls. and thermoelectric	USPAT; US-PGPUB	2003/08/13 16:22
	4	thermoelectric adj analyzer	USPAT; US-PGPUB	2004/02/20 15:02
	0	6570390.URPN.	USPAT	2003/08/13 16:24
	4	("4912052" "5097204" "5393980" "5543334").PN.	USPAT	2003/08/13 16:24

-	7	thermoelectric near2 analyzer	USPAT;	2004/02/20
-	1	"6570390"	US-PPGPUB	15:54
-	4	("4912052" "5097204" "5393980" "5543334").PN.	USPAT;	2004/02/20
-	5	indium near gold\$1tin near alloy	US-PPGPUB	15:02
-	251	324/\$.ccls. and thermoelectric	USPAT;	2004/02/20
-	61	(324/\$.ccls. and thermoelectric) and (indium gold)	US-PPGPUB	15:03
-	9758	hirayama.in.	USPAT	2004/02/20
-	22	hirayama.in. and (thermo\$1electric thermocouple)	US-PPGPUB	16:43
-	1	2003-203080.NRAN.	USPAT;	2004/02/20
-	16	324/451.ccls. and (thermo\$1electric thermocouple)	US-PPGPUB	16:44
-	4	324/451.ccls. and (thermo\$1electric thermocouple) and (indium gold)	USPAT;	2004/02/20
-	301	374/\$.ccls. and (thermo\$1electric thermocouple) and (indium gold)	US-PPGPUB	17:44
-	114	374/\$.ccls. and thermo\$1electric and (indium gold)	USPAT;	2004/02/20
-	17	374/\$.ccls. and thermo\$1electric and (indium gold) and adhesive	US-PPGPUB	17:44
-			EPO; JPO;	2004/02/20
-			DERWENT;	17:44
-			IBM_TDB	
-			EPO; JPO;	2004/02/20
-			DERWENT;	17:50
-			IBM_TDB	
-			DERWENT	2004/02/20
-				17:48
-				
-			USPAT;	2004/02/20
-			US-PPGPUB	17:53
-			USPAT;	2004/02/20
-			US-PPGPUB	17:57
-			USPAT;	2004/02/20
-			US-PPGPUB	17:58
-			USPAT;	2004/02/20
-			US-PPGPUB	17:59
-			USPAT;	2004/02/20
-			US-PPGPUB	17:59